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HITD U11
semi conductor device with lead frame for high density mounting - has outer lead exposed
sealing resin surface

ИИГАСИИ CABLE LTD 95.09.22 95JP-244204
(97.04.04) ИИ01L 23/50

The device includes a semi conductor chip (1) bonded with a lead frame (4). The lead frame consists of an inner lead (4a) and an outer lead (4b).
A bonding wire (9) is used to bond the inner lead frame and the semi conductor chip. A mould resin (8) is sealed on the surface of the semi conductor chip. The main body has outer lead exposed in a sealing resin surface (8a).

ADVANTAGE - Decreases package thickness. Prevents semi conductor chip from damage. (5pp Dwg.No.2/7)
U11-D03A1
97-259719

